

## SOT-23 Plastic-Encapsulate MOSFETS

### Features

- $V_{DS}=30V$
- $I_D=5.6A$
- $R_{DS(on)}@V_{GS}=10V < 27m\Omega$
- $R_{DS(on)}@V_{GS}=4.5V < 33m\Omega$
- Trench Power LV MOSFET technology
- Voltage controlled small signal switch
- Fast Switching Speed

**Drain-source Voltage**

30 V

**Drain Current**

5.6 Ampere

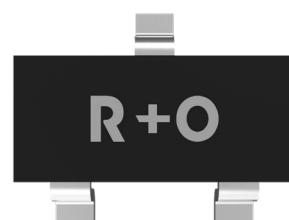
### Applications

- Battery protection
- Load switch
- Power management

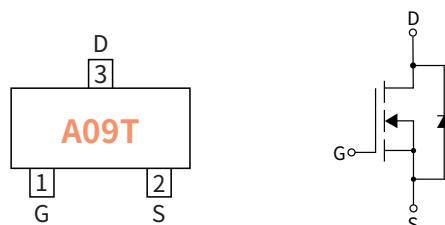
### Mechanical Data

- Case: SOT-23  
Molding compound meets UL 94V-0 flammability rating, RoHS-compliant, halogen-free
- Terminals: Solder plated, solderable per MIL-STD-750, Method 2026

**SOT-23**



### Function Diagram



### Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	VALUE
Drain-source Voltage	$V_{DS}$	V	30
Gate-source Voltage	$V_{GS}$	V	$\pm 12$
Drain Current	$I_D$	A	5.6
Pulsed Drain Current <sup>(1)</sup>	$I_{DM}$	A	23
Total Power Dissipation <sup>(2)</sup>	$P_D$	W	1.2
Junction temperature	$T_J$	°C	-55 ~ +150
Storage temperature	$T_{stg}$	°C	-55 ~ +150
Thermal Resistance Junction-to-Ambient @ Steady State <sup>(2)</sup>	$R_{\theta JA}$	°C / W	104

### Ordering Information

PACKAGE	PACKAGE CODE	UNIT WEIGHT(g)	REEL(pcs)	BOX(pcs)	CARTON(pcs)	DELIVERY MODE
SOT-23	R1	0.008	3000	45000	180000	7"

### ● Static Parameter Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	Condition	UNIT	Min	Typ	Max
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	V	30	—	—
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V	μA	—	—	1.0
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±12V, V <sub>DS</sub> =0V	nA	—	—	±100
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	V	0.65	0.9	1.5
Static Drain-Source On-Resistance <sup>(3)</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5.6A	mΩ	—	21	27
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =5.0A		—	25	33
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =3.0A		—	33	51
Gate resistance	R <sub>g</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =0, f=1MHz	Ω	—	—	3.6
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5.0V, I <sub>D</sub> =5.0A	S	8.0	—	—
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =5.6A, V <sub>GS</sub> =0V	V	—	—	1.2

### ● Dynamic Parameters (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	Condition	UNIT	Min	Typ	Max
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =15V V <sub>GS</sub> =0V f=1MHZ	pF	—	630	—
Output Capacitance	C <sub>oss</sub>			—	90	—
Reverse Transfer Capacitance	C <sub>rss</sub>			—	71	—

### ● Switching Parameters (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	Condition	UNIT	Min	Typ	Max
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =10V V <sub>DS</sub> =15V I <sub>D</sub> =5.6	nC	—	17	—
Gate-Source Charge	Q <sub>gs</sub>			—	2.0	—
Gate-Drain Charge	Q <sub>gd</sub>			—	2.0	—
Turn-on Delay Time	t <sub>D(on)</sub>	V <sub>GS</sub> =10V V <sub>DD</sub> =15V I <sub>D</sub> =5.6A R <sub>GEN</sub> =3.0Ω	ns	—	5.0	—
Turn-on Rise Time	t <sub>r</sub>			—	28	—
Turn-off Delay Time	t <sub>D(off)</sub>			—	16	—
Turn-off fall Time	t <sub>f</sub>			—	26	—

Note :

(1)Repetitive rating, pulse width limited by junction temperature T<sub>J(max)</sub>=150°C .Ratings are based on low frequency and duty cycles to keep initial T<sub>j</sub>=25°C .

(2)The value of P<sub>d</sub> and R<sub>0JA</sub> is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with T<sub>A</sub>=25°C .

(3)Pulse test: Pulse width ≤ 300us, duty cycle ≤ 2%.

● Ratings And Characteristics Curves (Ta=25°C Unless otherwise specified)

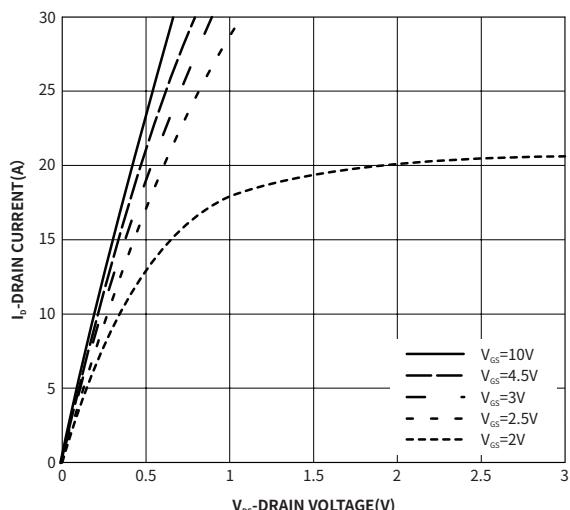


Fig.1 Output Characteristics

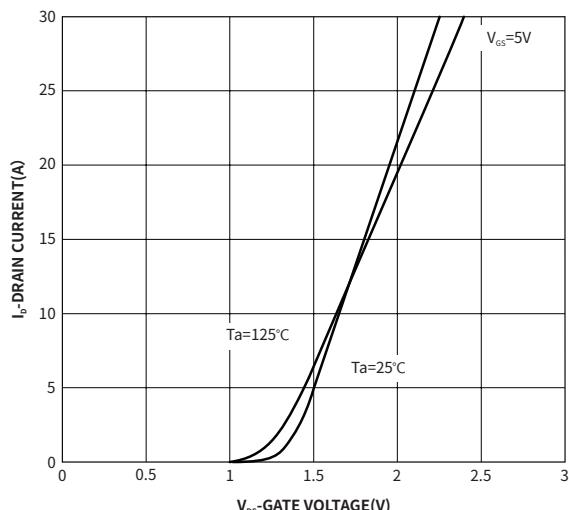


Fig.2 Transfer Characteristics

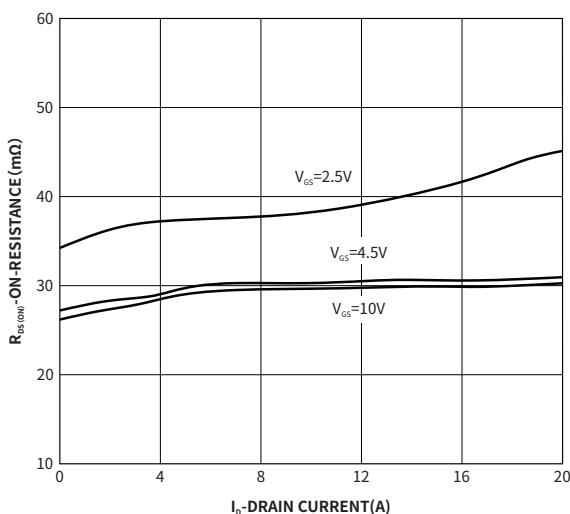


Fig.3 On-Resistance vs. Drain Current and Gate Voltage

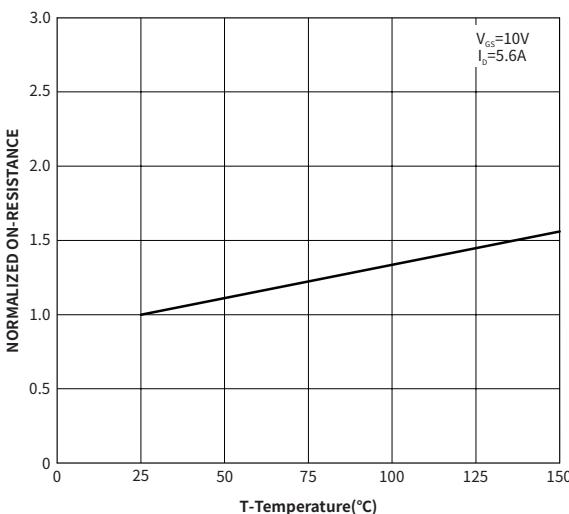


Fig.4 On-Resistance vs. Junction Temperature

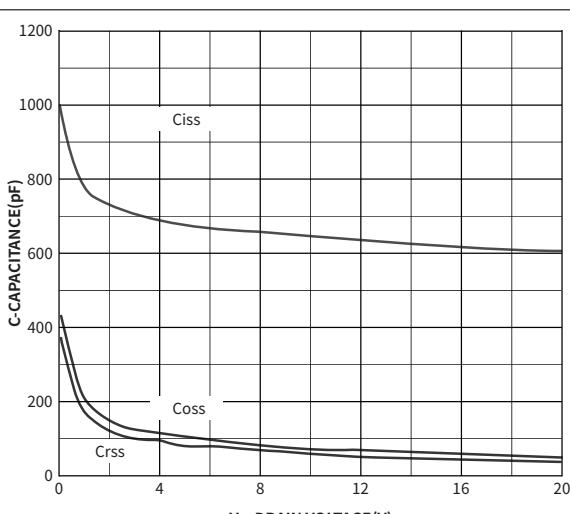


Fig.5 Capacitance Characteristics

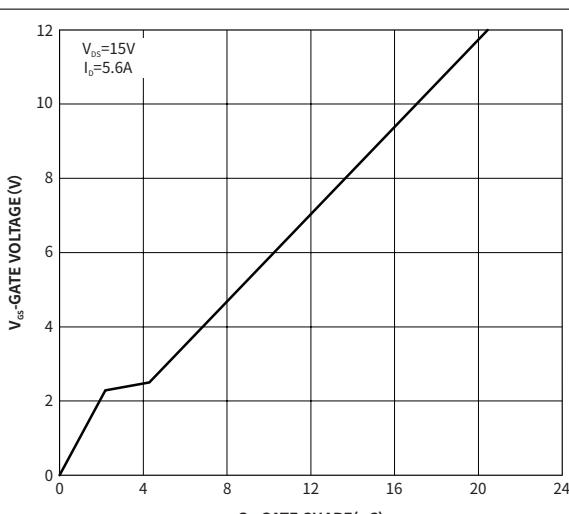


Fig.6 Gate Charge

● Ratings And Characteristics Curves (Ta=25°C Unless otherwise specified)

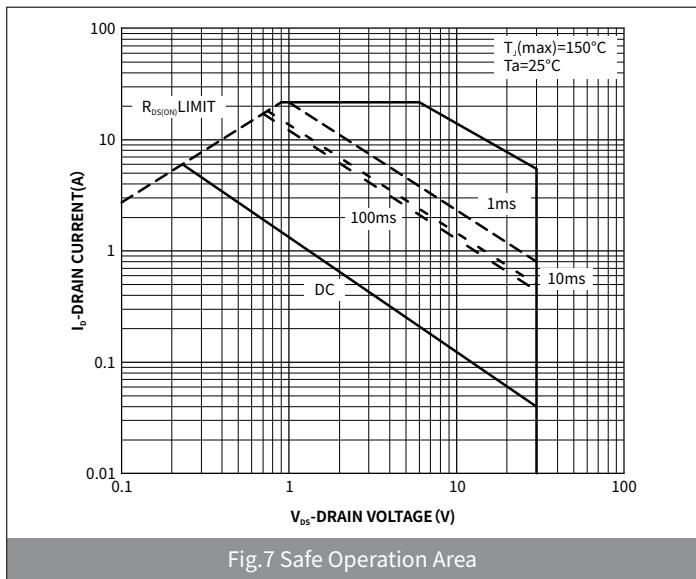


Fig.7 Safe Operation Area

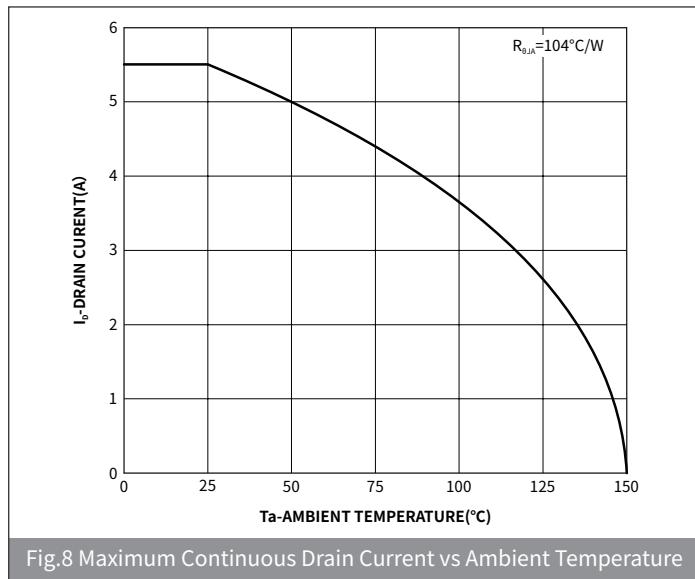


Fig.8 Maximum Continuous Drain Current vs Ambient Temperature

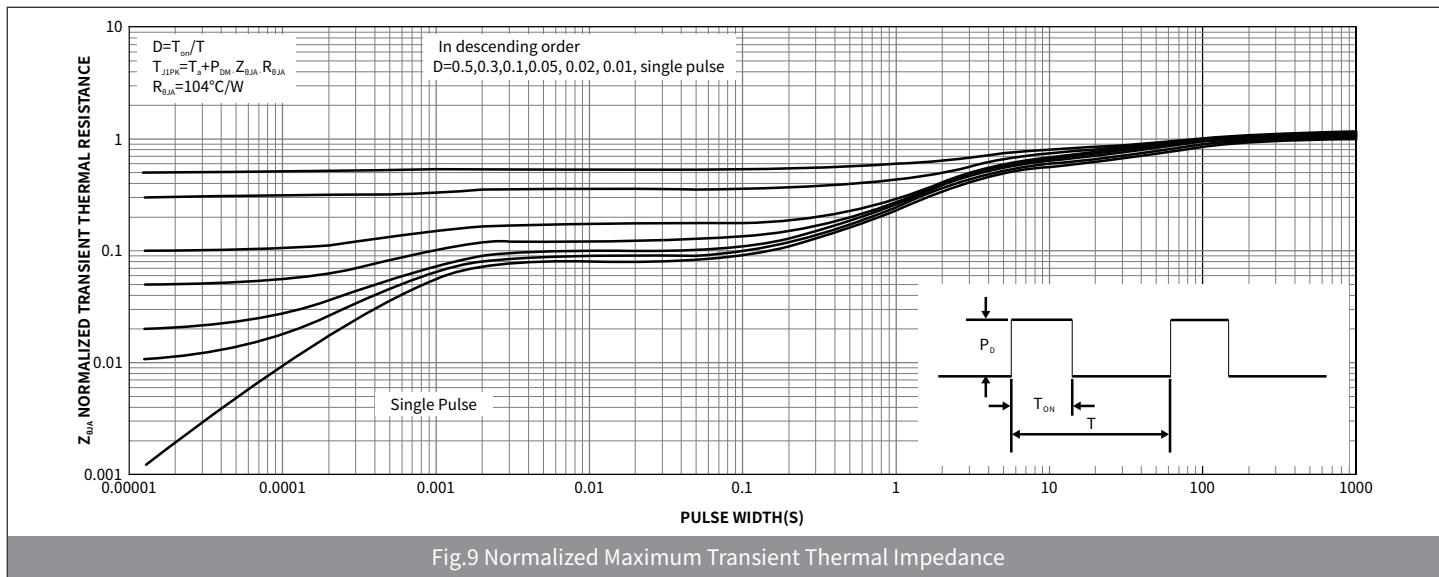
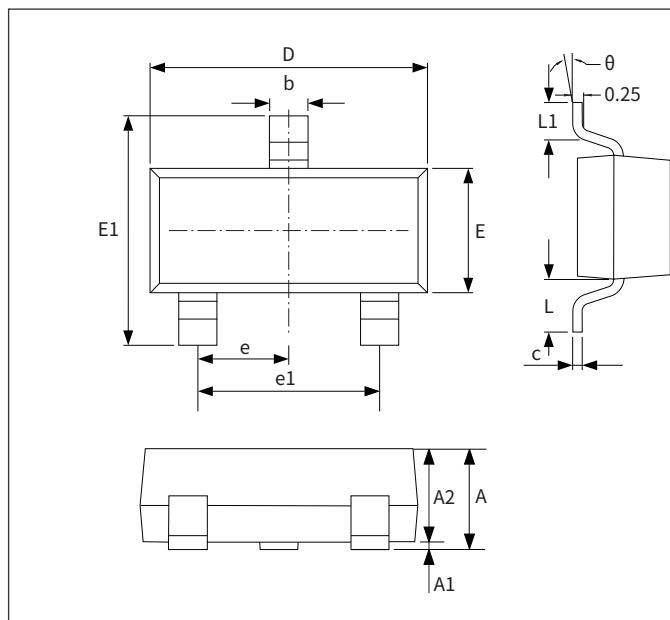


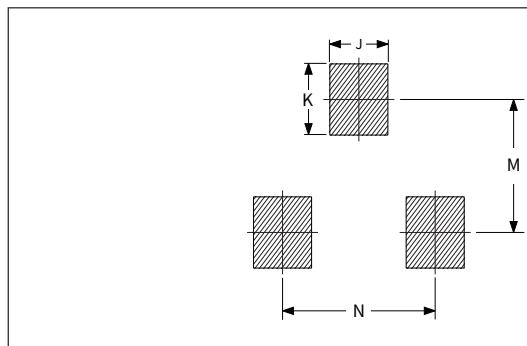
Fig.9 Normalized Maximum Transient Thermal Impedance

### ● Package Outline Dimensions (SOT-23)



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	0.90	1.15	0.035	0.045
A1	-	0.10	-	0.004
A2	0.90	1.05	0.035	0.041
b	0.30	0.50	0.012	0.020
c	0.10	0.20	0.004	0.008
D	2.80	3.00	0.110	0.118
E	1.20	1.40	0.047	0.055
E1	2.25	2.55	0.089	0.100
e	0.950TYP		0.037TYP	
e1	1.80	2.00	0.071	0.079
L	0.550REF		0.022REF	
L1	0.30	0.50	0.012	0.020
θ	-	8°	-	8°

### ● Suggested Pad Layout



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
J	0.75	0.85	0.030	0.033
K	0.85	0.95	0.033	0.037
M	1.95	2.05	0.077	0.081
N	1.85	1.95	0.073	0.077